

UNITED FOR EXCELLENCE

MEMS Deployment in a Ubiquitous Intelligence Era – Foundry View

Dr. Keh-Ching Huang Corporate Marketing UMC Apr. 2014

UMC Facts in One Slide

34 Years Experience

20 Years Pure-Play Foundry 16,000 Employees 1,100 R&D Engineers

500,000 wpm Capacity

12" Fab x2 8" Fab x7 6" Fab x1





\$4B Revenue

24% from <=40nm

28nm Ramp Up 2Q14

14nm Pilot 2014/E



Outline

- All Good Things...
- Next Semiconductor Driving Force
 - IoT
 - Wearable
- MEMS Enablement Proposal
- Summary

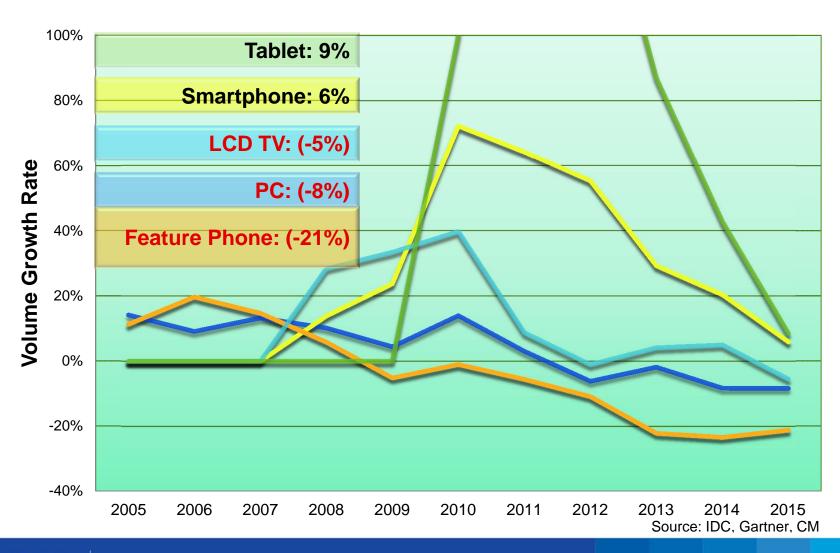
All good things, must come to an end...

Title of final episode of Star Trek, The Next Generation Geoffrey Chaucer, father of English literature



Advanced Technology Driver Out of Steam

Just like everthing else...



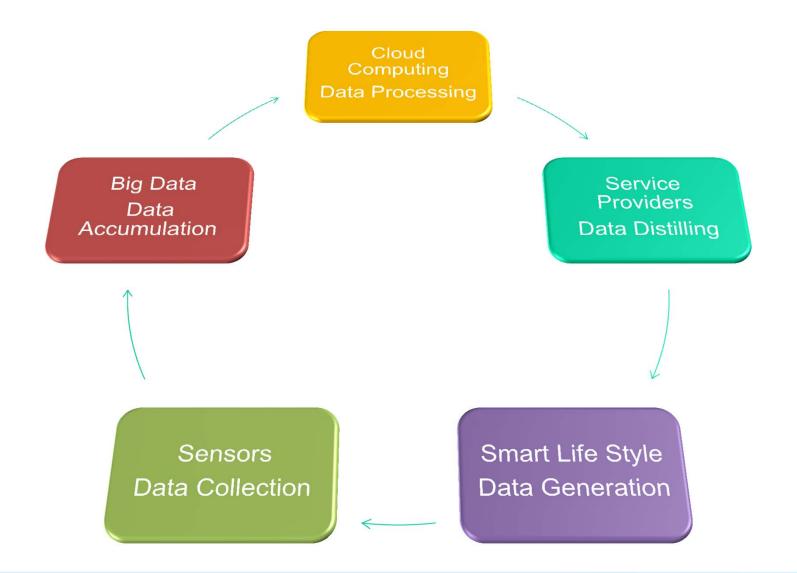
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Learn to see and realize that everything connects to everything else.

Leonardo Da Vinci

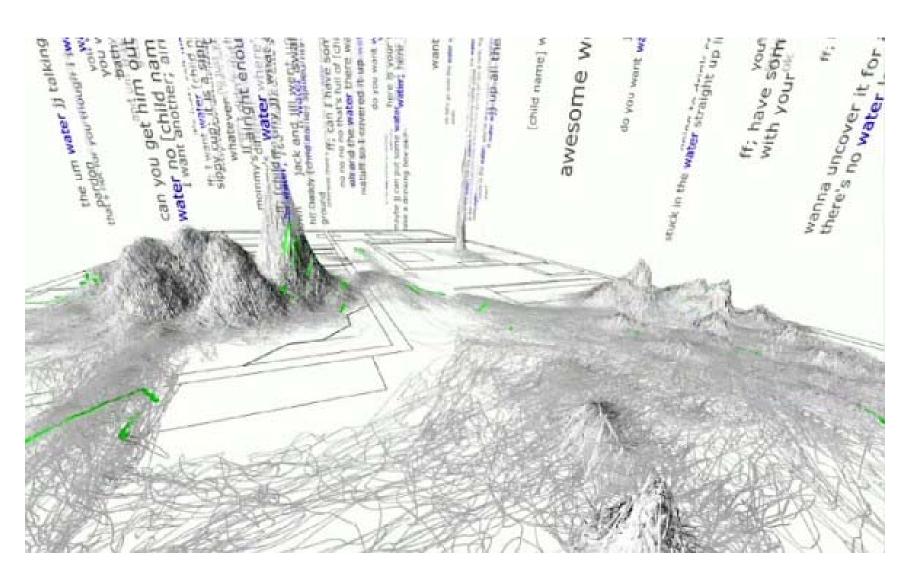


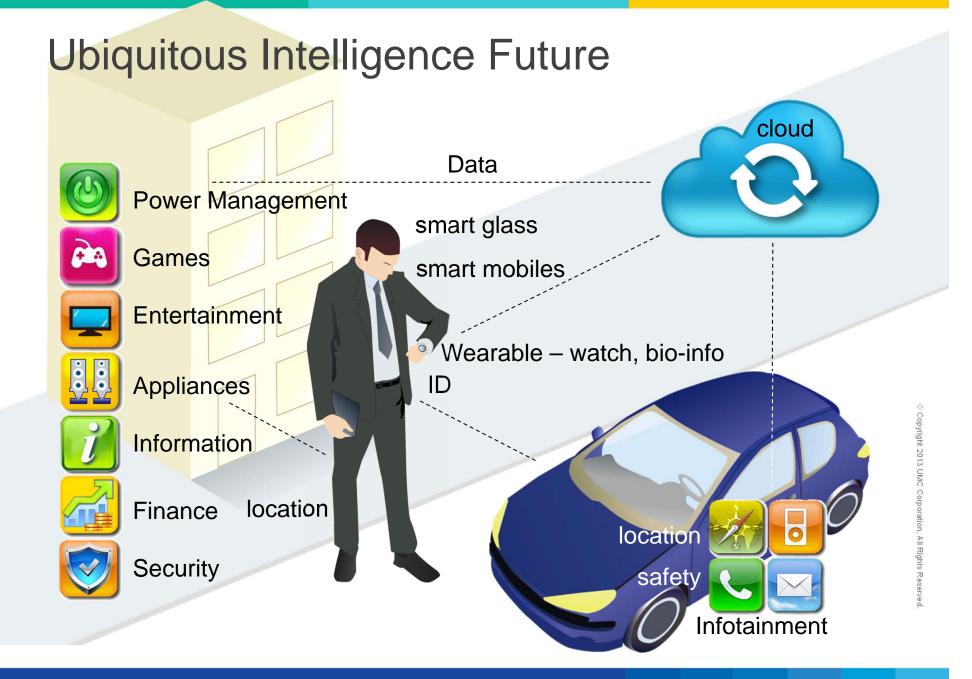
Data Alchemy Drives The Need



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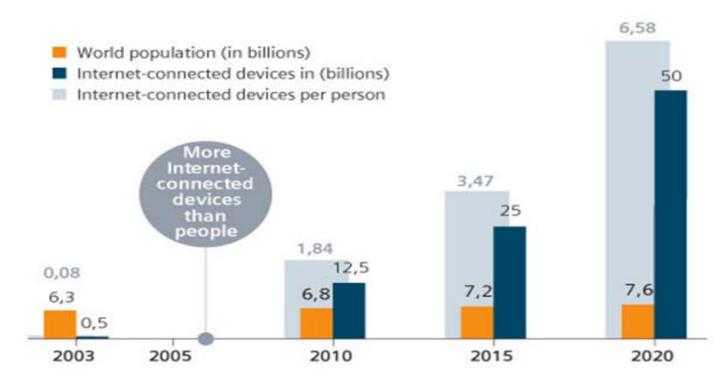
IoT, Big Data and Cloud Computing





WW IoT Market Prospect

- IoT market by 2020
 - 50bn units
 - US\$ Trillions



Source: Cisco IBSG, April 2011

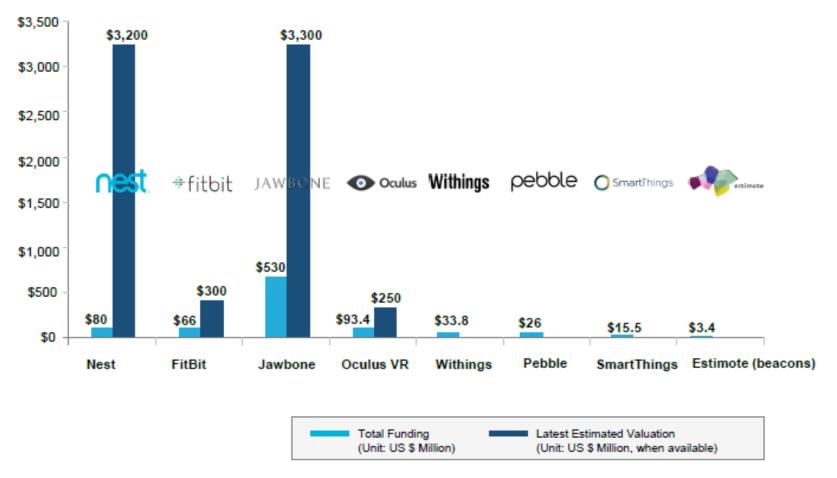
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WW IoT Advocators

- Top 5 IoT Countries
 - USA, EU, South Korea, Japan, China
- Major government projects
 - China
 - Important tasks and major projects of "12th Five-Year Development Plan"
 - IoT Centers, Shanghai, Wuxi, and Guangdong
 - Europe
 - IERC, IOT European Research Cluster, is a cooperation platform and develop a research vision for IOT activities in Europe

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'Internet Of Things', Where The Money Goes



Source: Business Intelligence, The Internet of Everything: 2014

Confidential

12

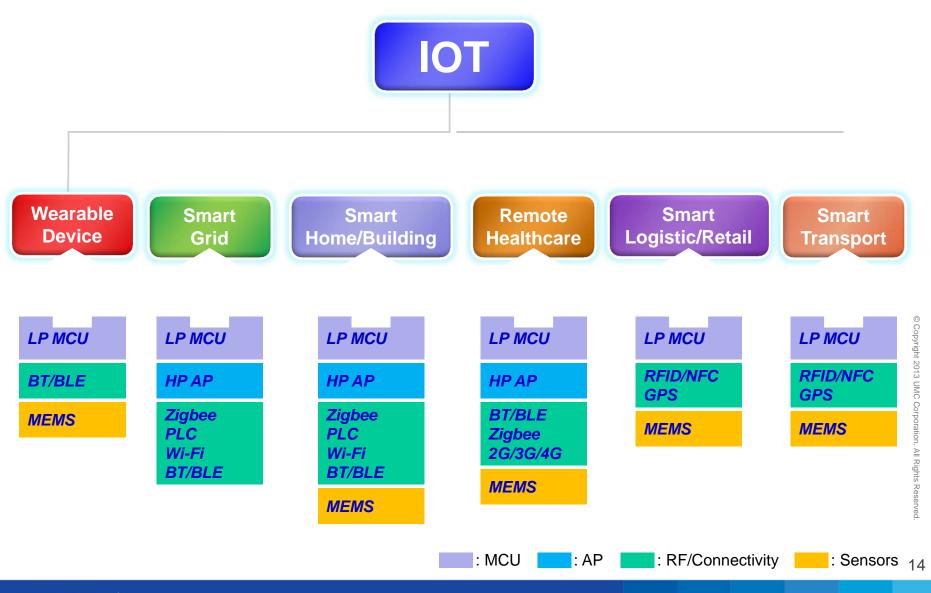
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IoT Engine Revving Up

Inflection at 2017, enough time for preparation

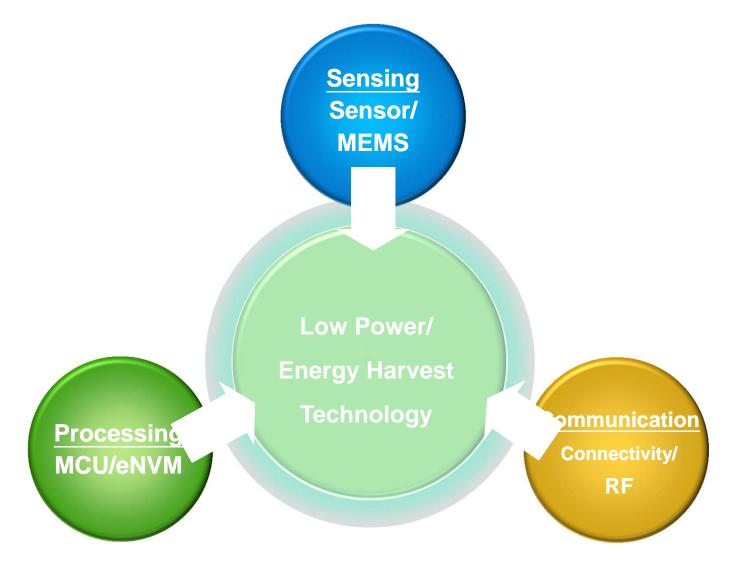
- 5 quintillion byte data per day generated
- 50B devices by 2020, inflection point 2017
 - >30% CAGR from 2013 to 2020
 - >200KWPM (12in) in 2020
- Market fragmented, commodity process won't cut it!
 - System knowhow, tailor-made processes, partnership
- Most devices in mature nodes, but new requirements, especially power the major concern.

Main IOT Applications & Key Technologies



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IOT Solution at Low Power Platform

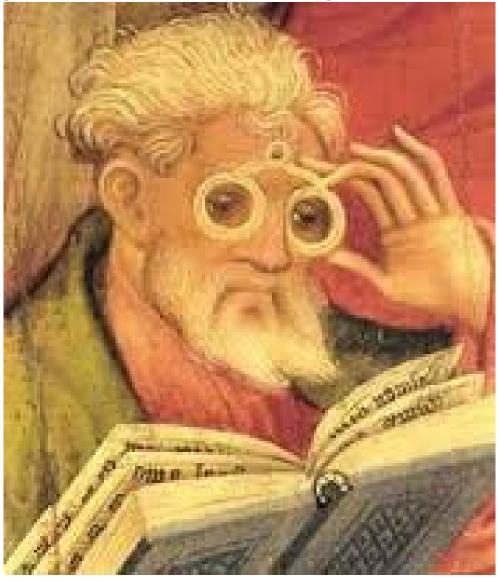


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15

A Wearable Deluge











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IoT Can Be A Blessing or Curse...



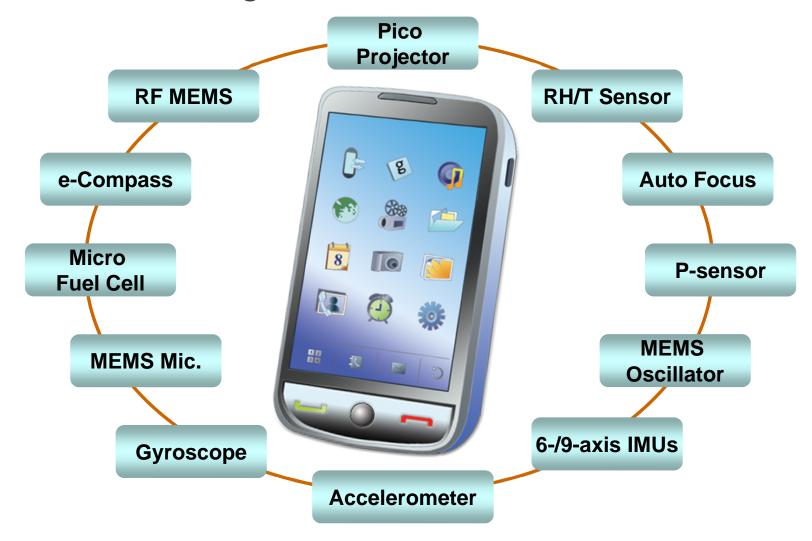




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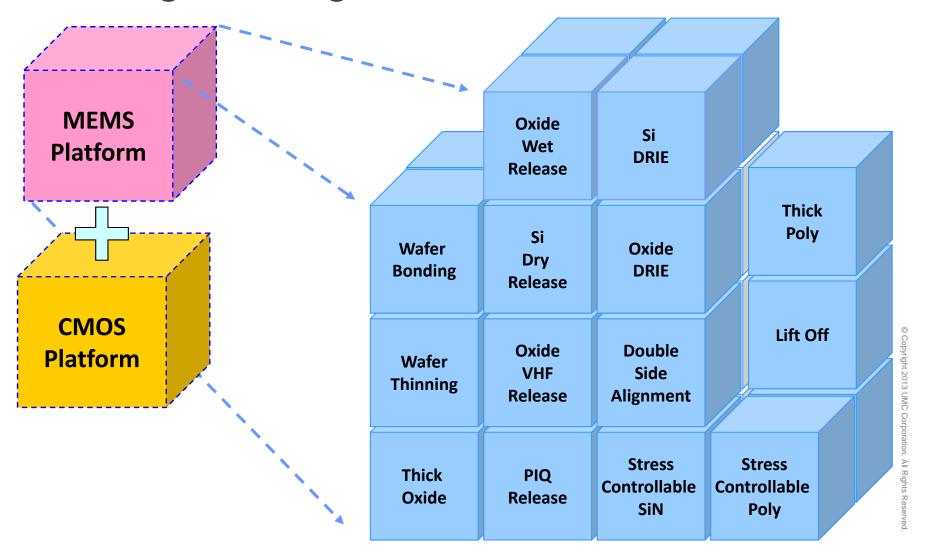
How Will MEMS Participate in IoT Party?

Diversified Usage Scenarios for MEMS Sensors



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Existing Working Model: Modular Process



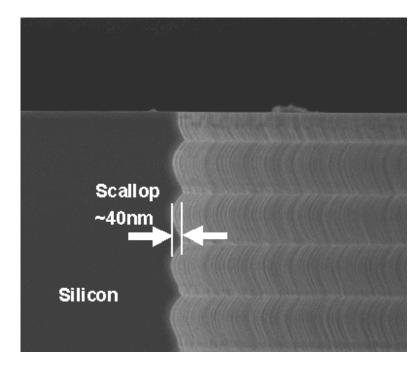
MEMS Modules Production Examples

Application	Double Side Aligner	Si DRIE	Ox DRIE	PIQ release	Ox Vapor HF	Wet Ox HF release	Pt dry etch
Micro- phone A	V	V				V	
Micro- phone B	V	V	V	V			
Micro-phone C (CMOS+ MEMS)	V	V				V	
Accelerometer					V		
Gas sensor	V	V	V				V

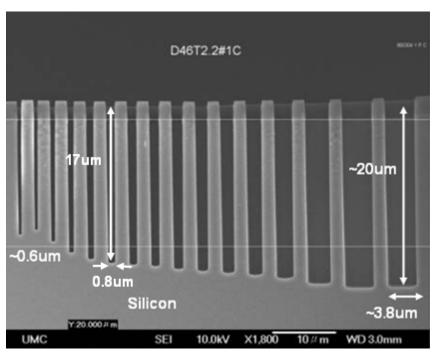
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DRIE Process for Si Etching

Scallop control vs process through-put



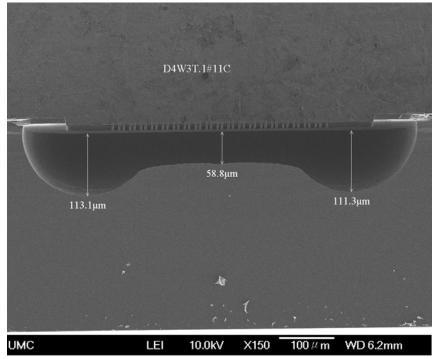
Scallop control of DRIE Bosch Si etching



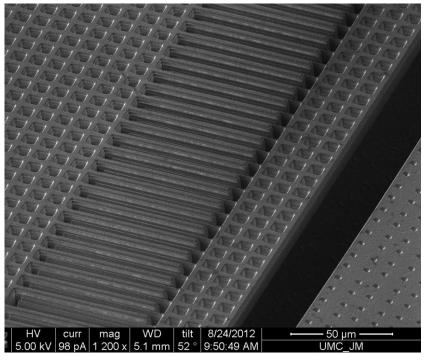
Through-pitch profile control of DRIE Bosch Si etching

Oxide DRIE & Isotropic Si Etching

MEMS structure fine tuning by Oxide+Si DRIE



Cross section of accelerometer with silicon released underneath

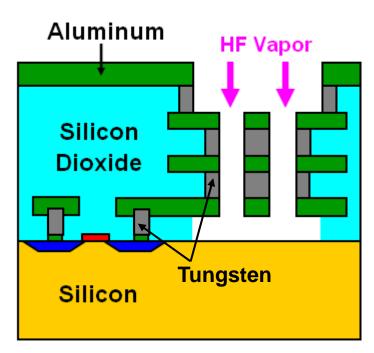


Top view of MEMS structure with silicon released underneath

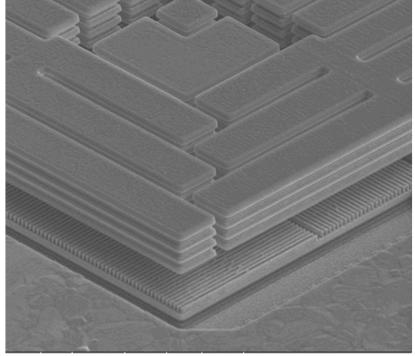
Oxide Release Process

 Vapor HF (dry) oxide release process uniformity control vs. through-put

Pattern loading effect considerations



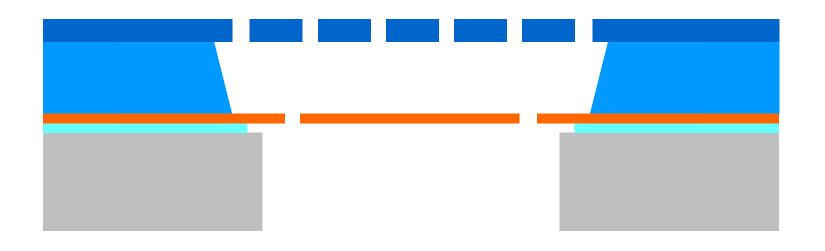
Process scheme of VHF oxide release



SEM view of MEMS structure after VHF oxide release

Difficulties Persist With Modulized Processes...

- Film stress control
 - Chemistry, temparature, RF Power, ...
- Chamber release uniformity
 - Etching recipe, drying procedures, ...



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More than a year proces tuning typically Lose-lose case for customer and foundry Things need to be done differently!

An Open MEMS Design Environment Proposed

Fine grain process modules Accurate model database Package-aware service flow

34

Summary

- IoT will drive MEMS shipment
- MEMS market diversified, process development cycle too long
 - Slow time to market, high entry barrier, deter innovation
- Cowork with supply chain to facilitate delivery
 - Fine grain process modules
 - Accurate model database
 - Package-aware service flow

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Thank You

